Cold Electronics Quality Control

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QC Meeting 23 February 2024





Introduction

- So far we have a number of smaller subgroup meetings focusing on specific QC issues. As we are approaching the start of FD1/FD2 production, we would like to consolidate the QC meetings
- Initially we will focus on ASIC QC issues. FEMB QC will be next follow by others
- Executing CD-3a scope now. Mostly buying FD1 components for PTC, WIB, and FEMB
- CD-3b scope will allow us to start fabricating a fraction of the FEMBs for FD1 and FD2. Expecting CD-3b ESAAB approval from DOE any minute now
- Planning for the FD1 and FD2 Production Readiness Review for FEMB around end of May/beginning of June
- Need to ramp up QC effort → the focus of this QC group
- Thanks to Jon for agreeing to lead this effort



We have a master QC plan in <u>EDMS#2815079</u>. It's a living document, will update as we learn more from the process

LBNF/DUNE-US
DUNE FD1 Time Projection Chamber
(TPC) Electronics and FD2 Bottom Drift
Electronics (BDE) Quality Control Plan

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- Expectation for this group:
 - Maintain the master QC plan (high level plan)
 - Work with various subsystem experts to develop and document (in EDMS) detailed QC instructions, check list, travelers, etc.
 - Work with CE Database Group (led by Martin Tzanov + a BNL postdoc?) to centralize the storage of QC data
 - Bring up QC sites at various institutions
 - Ensure uniformity across different QC sites: BNL, FNAL, LBNL,
 MSU, LSU, Irvine, Cincinnati, Iowa State, Florida, CSU
 - First two priorities are:
 - 1. ASIC test-stands (~ summer to have all 6 sites operational)
 - 2. FEMB test-stands (bring up sites from ~ summer to end of 2024)
- Fabrication of the first batch of production FEMBs will start ~ summer of 2024



- Preparation for the FD1+FD2 FEMB Production Readiness Review requires a fairly extensive list of documents (excerpt of <u>EDMS#2493568</u> from Technical Coordination):
 - The QC Plan should include:
 - ✓ Applicable specifications, drawings, and procedures
 - ✓ List of components to be inspected and tested
 - ✓ Tests to be performed
 - ✓ Location where tests will be performed
 - ✓ Descriptions of technical requirements being verified by each inspection and tests
 - Develop traveller documents (e.g from QC sites to SURF)
 - Plan for documentation of non-conforming items
 - Documentation of assigned responsibilities for who signs-off on each step in the QC process

